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MCCOG128064C6WD-F	CCOG128064C6WD-FPTLW 128		Parallel	LCD Module			
	Specification						
Version:	4		Date: 26/02/2016				
			Revision				
1	14/08/2009	First is	sue.				
2	03/09/2012	Add R	Add Recommendable storage.				
3	20/01/2016	Remov	ve IC information.				
4	25/02/2016	Modify	et Absolute Maximum Ratings & Responder cable 100±8.0MM. Precautions in use of LCD Modules				

Display F			
Resolution	128 x 64		
Appearance	Black on White		
Logic Voltage	3V		
Interface	Parallel		4
Font Set	English / Japanese		COHS Ompliant
Display Mode	Transflective		muliant
LC Type	FSTN		Jiliplialit
Module Size	89.70 x 49.80 x 6.00mm		
Operating Temperature	-20°C ~ +70°C		
Construction	mancogactiin	 Box Quantity 	Weight / Display
LED Backlight	White	<u> </u>	

 * - For full design functionality, please use this specification in conjunction with the ST7565P-G specification. (Provided Separately)

Display Accessories					
Part Number	Description				
MCCOG-I2C-I-8	Fine pitch(1.27mm) COG I2C interface board. Compatible with both Arduino and UC32 controller boards.				

Optional Variants						
Fonts	Appearances	Voltage				

General Specification

The Features is described as follow:

■ Module dimension: 89.7x 49.8 x6.0 (max.) mm

■ View area: 69.0 x 36.5 mm

Active area: 63.97 x31.97 mm

■ Number of dots: 128 x 64

■ Dot size: 0.47 x0.47 mm

■ Dot pitch: 0.5 x 0.5 mm

■ LCD type: FSTN Positive Transflective

■ Duty: 1/65 , 1/9 Bias

■ View direction: 6 o'clock

■ Backlight Type: LED White

■ IC: ST7565P

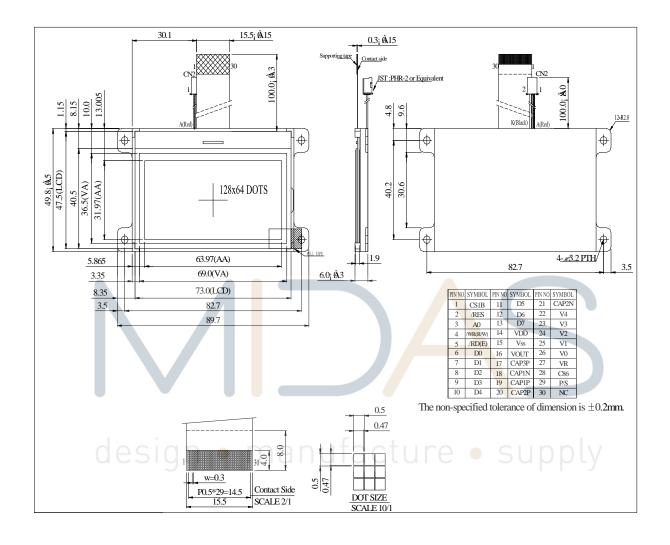
design • manufacture • supply

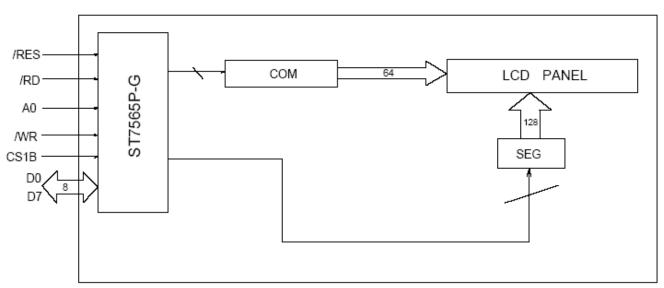
Interface Pin Function

Pin No.	Symbol	I/O	Description
1	/CS1B	I	This is the chip select signal.
2	/RES	I	When RES is set to "L", the setting are initialized.
3	A0	I	This is connect to the least significant bit of the normal MPU address bus, and it determines whether the data bits are data or command. A0 = "H": Indicates that D0 to D7 are display data. A0 = "L": Indicates that D0 to D7 are control data.
4	/WR(R/W)	1	 When connected to 8080 series MPU, this pin is treated as the "/WR" signal of the 8080 MPU and is LOW-active. The signals on the data bus are latched at the rising edge of the /WR signal. When connected to 6800 series MPU, this pin is treated as the "R/W" signal of the 6800 MPU and decides the access type: When R/W = "H": Read. When R/W = "L": Write.
5	desig /RD(E)	n • I	 When connected to 8080 series MPU, this pin is treated as the "/RD" signal of the 8080 MPU and is LOW-active. The data bus is in an output status when this signal is "L". When connected to 6800 series MPU, this pin is treated as the "E" signal of the 6800 MPU and is HIGH-active. This is the enable clock input terminal of the 6800 Series MPU.
6~13	D0~ D7	I/O	Data bus line
14	VDD	Power Supply	Power supply
15	VSS	Power Supply	Ground
16	VOUT	0	DC/DC voltage converter. Connect a capacitor between this terminal and vss or VDD
17	CAP3P	0	DC/DC voltage converter. Connect a capacitor between this terminal and the CAP1N terminal.
18	CAP1N	0	DC/DC voltage converter. Connect a capacitor between this terminal and the CAP1P terminal.

19	CAP1P	0		DC/DC voltage converter. Connect a capacitor between this terminal and the CAP1N terminal.							
20	CAP2P	0	DC/DC	DC/DC voltage converter. Connect a capacitor between this terminal and the CAP2N terminal.							
21	CAP2N	0		DC/DC voltage converter. Connect a capacitor between this terminal and the CAP2P terminal.							
22~26	V4~ V0	Power Supply	This is a drive.	a multi-level po	wer supp	ly for the li	quid crystal				
27	VR	I	between IRS = "L not use	Output voltage regulator terminal. Provides the voltage between VSS and V0 through a resistive voltage divider. IRS = "L": the V0 voltage regulator internal resistors are not used. IRS = "H": the V0 voltage regulator internal resistors are used.							
28	C86	1	C86 = "	This is the MPU interface selection pin. C86 = "H": 6800 Series MPU interface. C86 = "L": 8080 Series MPU interface							
	desig	n • 1	terminal P/S = "H P/S = "L The follo	This is the parallel data input/serial data input switch terminal. P/S = "H": Parallel data input. P/S = "L": Serial data input. The following applies depending on the P/S status:							
29	P/S	I	P/S	Data/Command	Data	Read/Write	Serial Clock				
			"H"	A0	D0 to D7	/RD, /WR	Х				
			"L"	A0	SI (D7)	Write only	SCL (D6)				
			/RD (E)	/S = "L", D0 to and /WR (R/W rial data input, I) are fixed			м			
30	NC	-	No conr	nection.							

Contour Drawing & Block Diagram



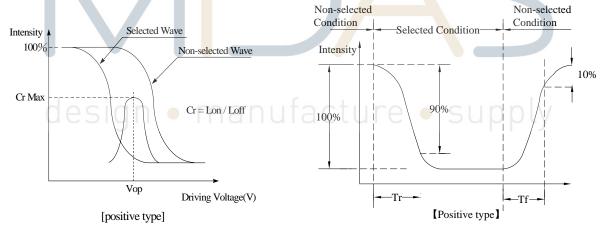


Optical Characteristics

Item	Symbol	Condition	Min	Тур	Max	Unit
	θ	CR ≧ 2	0	_	30	ψ= 180°
Miour Applo		ψ= 0°				
View Angle	θ	CR ≧ 2	0	_	45	ψ= 90°
	θ	CR ≧ 2	0	_	45	ψ= 270°
Contrast Ratio	CR	_	_	5	_	_
Danie Time	T rise	_	_	200	300	ms
Response Time	T fall		7	250	60 45 45	ms

Definition of Operation Voltage (Vop)

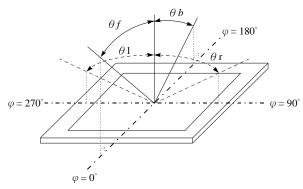
Definition of Response Time (Tr, Tf)



Conditions:

Frame Frequency: 64 HZ Driving Waveform: 1/N duty, 1/a bias

Definition of viewing angle(CR≥2)



Absolute Maximum Ratings

Item	Symbol	Min	Тур	Max	Unit
Operating Temperature	Тор	-20	_	+70	
Storage Temperature	T _{ST}	-30	_	+80	
Power Supply Voltage	VDD	-0.3	_	3.6	V
Power supply voltage (VDD standard)	V0, VOUT	-0.3	_	14.5	V
Power supply voltage (VDD standard)	V1, V2, V3, V4	-0.3	_	V0+0.3	V



Electrical Characteristics

Item	Symbol	Condition	Min	Тур	Max	Unit
Supply Voltage For Logic	V _{DD} -V _{SS}	_	2.7	_	3.3	V
		Ta=-20	9.5	9.8	10.5	V
Supply Voltage For LCM	Vo-Vss	Ta=25	9.2	9.45	9.7	V
		Ta=70	8.95	9.2	9.45	V
Input High Volt.	VIH	_	0.8 V _{DD}	_	V_{DD}	V
Input Low Volt.	VıL	_	Vss	_	0.2 V _{DD}	V
Output High Volt.	V _{OH}	I _{ОUТ} =-0.5mA	0.8 V _{DD}	-	V_{DD}	V
Output Low Volt.	Vol	I _{OUT} =0.5mA	Vss	_	0.2V _{DD}	V
Supply Current(No						
include	I _{DD}		_	0.60	2.0	mA
LED Backlight)						
NOTE 1: 1) Duty ratio=1/	65, Bias=1/9	iuract	ure	• 5	uppt	. У

2) Measured in Dots ON-state

NOTE 2: Please kindly consider to design the Vop to be adjustable while programing the software to match LCD contrast tolerance

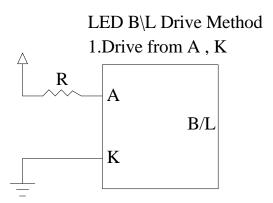
Backlight Information

Specification

PARAMETER	SYMBOL	MIN	TYP	мах	UNIT	TEST CONDITION
Supply Current	ILED	_	64	80	mA	V=3.5V
Supply Voltage	V	3.4	3.5	3.6	V	_
Reverse Voltage	VR	_	_	5	V	_
Luminance (Without LCD)	IV	650	820	_	CD/M ²	ILED=64mA
LED Life Time	-1	-	50K		Hr.	ILED <i>≦</i> 64mA 25 ,50-60%RH
Color	White					

Note: The LED of B/L is drive by current only, drive voltage is for reference only. drive voltage can make driving current under safety area (current between minimum and maximum).

Note1:50K hours is only an estimate for reference.



Reliability

Content of Reliability Test (Wide temperature, -20~70)

	Environmental Test								
Test Item	Content of Test	Test Condition	Note						
High Temperature storage	Endurance test applying the high storage temperature for a long time.	200hrs	2						
Low Temperature storage	Endurance test applying the low storage temperature for a long time.	-30 200hrs	1,2						
High Temperature Operation	Endurance test applying the electric stress (Voltage & Current) and the thermal stress to the element for a long time.	70 200hrs							
Low Temperature Operation	Endurance test applying the electric stress under low temperature for a long time.	-20 200hrs	1						
High Temperature/ Humidity storage	The module should be allowed to stand at 60 ,90%RH max For 96hrs under no-load condition excluding the polarizer, Then taking it out and drying it at normal temperature.	60 ,90%RH 96hrs	1,2						
Thermal shock resistance	The sample should be allowed stand the following 10 cycles of operation -20 25 70 30min 5min 30min 1 cycle	-20 /70 10 cycles							
Vibration test	Endurance test applying the vibration during transportation and using.	Total fixed amplitude: 1.5mm Vibration Frequency: 10~55Hz One cycle 60 seconds to 3 directions of X,Y,Z for Each 15 minutes	3						
Static electricity test	Endurance test applying the electric stress to the terminal.	VS=±600V(contact), ±800v(air), RS=330 Ω CS=150pF 10 times							

Note1: No dew condensation to be observed.

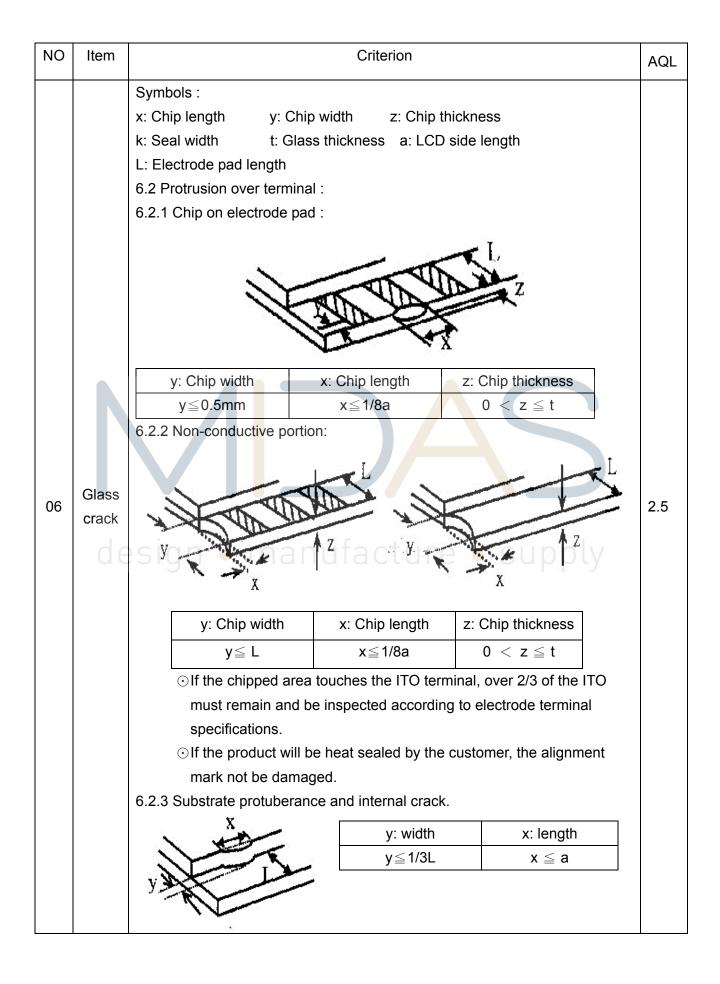
Note2: The function test shall be conducted after 4 hours storage at the normal Temperature and humidity after remove from the test chamber.

Note3: The packing have to including into the vibration testing.

Inspection specification

NO	Item			Criterion		AQL		
01	Electrical Testing	 1.1 Missing vertical, horizontal segment, segment contrast defect. 1.2 Missing character, dot or icon. 1.3 Display malfunction. 1.4 No function or no display. 1.5 Current consumption exceeds product specifications. 1.6 LCD viewing angle defect. 1.7 Mixed product types. 1.8 Contrast defect. 						
02	Black or white spots on LCD (display only)	three white o	2.1 White and black spots on display ≤0.25mm, no more than three white or black spots present.2.2 Densely spaced: No more than two spots or lines within 3mm					
03	LCD black spots, white	3.1 Round type Φ=(x + y) / 3.2 Line type : (a	Y nufa	$Φ \le 0.10$ $0.10 < Φ \le 0.20$ $0.20 < Φ \le 0.25$ $0.25 < Φ$	Acceptable Q TY Accept no dense 2 1 0 SUPPLY Acceptable Q TY	2.5		
(non-di	(non-display)	non-display) → L W —————————————————————————————————	 L≦3.0 L≦2.5	$\begin{array}{c} W \! \leq \! 0.02 \\ 0.02 \! < \! W \! \leq \! 0.03 \\ 0.03 \! < \! W \! \leq \! 0.05 \\ 0.05 \! < \! W \end{array}$	Accept no dense 2 As round type	2.5		
04	Polarizer bubbles	If bubbles are vijudge using black specifications, note to find, must che specify direction	ck spot ot easy eck in	Size Φ $Φ \le 0.20$ $0.20 < Φ \le 0.50$ $0.50 < Φ \le 1.00$ $1.00 < Φ$ Total Q TY	Acceptable Q TY Accept no dense 3 2 0 3	2.5		

NO	Item	Criterion				
05	Scratches	Follow NO.3 LCD black spots, white spots, contamination				
	Chipped glass	Symbols Define: x: Chip length y: Chip width z: Chip thickness k: Seal width t: Glass thickness a: LCD side length L: Electrode pad length: 6.1 General glass chip: 6.1.1 Chip on panel surface and crack between panels:				
		z: Chip thickness Z≤1/2t	y: Chip width Not over viewing	x: Chip length x≤1/8a		
06		1/2t <z≦2t< td=""><td>area Not exceed 1/3k</td><td>x≦1/8a</td><td>2.5</td></z≦2t<>	area Not exceed 1/3k	x≦1/8a	2.5	
		Olf there are 2 or more chips, x is total length of each chip. 6.1.2 Corner crack:				
			area			
		1/2t < z ≦ 2t	Not exceed 1/3k	x≦1/8a		
		⊙ If there are 2 or more	chips, x is the total len	gth of each chip.		



NO	Item	Criterion	AQL	
07	Cracked glass	The LCD with extensive crack is not acceptable.		
08	Backlight elements	 8.1 Illumination source flickers when lit. 8.2 Spots or scratched that appear when lit must be judged. Using LCD spot, lines and contamination standards. 8.3 Backlight doesn't light or color wrong. 		
09	Bezel	9.1 Bezel may not have rust, be deformed or have fingerprints, stains or other contamination.9.2 Bezel must comply with job specifications.		
		 10.1 COB seal may not have pinholes larger than 0.2mm or contamination. 10.2 COB seal surface may not have pinholes through to the IC. 10.3 The height of the COB should not exceed the height indicated in the assembly diagram. 10.4 There may not be more than 2mm of sealant outside the seal area on the PCB. And there should be no more than 	2.5 2.5 0.65	
10	PCB · COB	three places. 10.5 No oxidation or contamination PCB terminals. 10.6 Parts on PCB must be the same as on the production characteristic chart. There should be no wrong parts, missing parts or excess parts. 10.7 The jumper on the PCB should conform to the product characteristic chart. 10.8 If solder gets on bezel tab pads, LED pad, zebra pad or screw hold pad, make sure it is smoothed down. 10.9 The Scraping testing standard for Copper Coating of PCB	2.5 0.65 0.65 2.5	
11	Soldering	11.1 No un-melted solder paste may be present on the PCB. 11.2 No cold solder joints, missing solder connections, oxidation or icicle. 11.3 No residue or solder balls on PCB. 11.4 No short circuits in components on PCB.	2.5 2.5 2.5 0.65	

NO	Item	Criterion		
		12.1 No oxidation, contamination, curves or, bends on interface Pin (OLB) of TCP.		
	General appearance	12.2 No cracks on interface pin (OLB) of TCP.		
		12.3 No contamination, solder residue or solder balls on product.		
		12.4 The IC on the TCP may not be damaged, circuits.		
		12.5 The uppermost edge of the protective strip on the interface	2.5	
		pin must be present or look as if it cause the interface pin to		
		sever.		
12		12.6 The residual rosin or tin oil of soldering (component or chip		
		component) is not burned into brown or black color.		
		12.7 Sealant on top of the ITO circuit has not hardened.		
		12.8 Pin type must match type in specification sheet.	0.65 0.65	
		12.9 LCD pin loose or missing pins.	0.65	
		12.10 Pr <mark>o</mark> duct packaging must th <mark>e same as s</mark> pecified on		
		packaging specification sheet.		
		12.11 Product dimension and structure must conform to product	0.65	
		specification sheet.		
	design	12.12 Visual defect outside of VA is not considered to be rejection.		

Precautions in use of LCD Modules

- (1)Avoid applying excessive shocks to the module or making any alterations or modifications to it.
- (2)Don't make extra holes on the printed circuit board, modify its shape or change the components of LCD module.
- (3)Don't disassemble the LCM.
- (4)Don't operate it above the absolute maximum rating.
- (5)Don't drop, bend or twist LCM.
- (6)Soldering: only to the I/O terminals.
- (7)Storage: please storage in anti-static electricity container and clean environment.
- (8) T aaæ have the right to change the passive components, including R3,R6 & backlight adjust resistors. (Resistors, capacitors and other passive components will have different appearance and color caused by the different supplier.)
- (9) AT at the have the right to change the PCB Rev. (In order to satisfy the supplying stability, management optimization and the best product performance...etc, under the premise of not affecting the electrical characteristics and external dimensions, T at the have the right to modify the version.)
- (10) To ensure the stability of the display screen, please apply screen saver after showing 30 mins of fixed display content.



Material List of Components for RoHs

1. T aaæ hereby declares that all of or part of products (with the mark "#"in code), including, but not limited to, the LCM, accessories or packages, manufactured and/or delivered to your company (including your subsidiaries and affiliated company) directly or indirectly by our company (including our subsidiaries or affiliated companies) do not intentionally contain any of the substances listed in all applicable EU directives and regulations, including the following substances.

Exhibit A: The Harmful Material List

Material	(Cd)	(Pb)	(Hg)	(Cr6+)	PBBs	PBDEs	
Limited Value	100 ppm	1000 ppm	1000 ppm	1000 ppm	1000 ppm	1000 ppm	
Above limited value is set up according to RoHS.							

- 2.Process for RoHS requirement : (only for RoHS inspection)
 - (1) Use the Sn/Ag/Cu soldering surface; the surface of Pb-free solder is rougher than we used before.
 - (2) Heat-resistance temp. :

Reflow: 250 ,30 seconds Max.;

Connector soldering wave or hand soldering: 320 , 10 seconds max.

(3) Temp. curve of reflow, max. Temp.: 235±5;

Recommended customer's soldering temp. of connector: 280, 3 seconds.

Recommendable Storage

- 1. Place the panel or module in the temperature 25°C±5°C and the humidity below 65% RH
- 2. Do not place the module near organics solvents or corrosive gases.
- 3. Do not crush, shake, or jolt the module.